

MULTI-INNO TECHNOLOGY CO., LTD.

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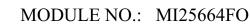
OLED MODULE SPECIFICATION

Model : MI25664FO

For Customer's Acceptance:

Customer		
Approved		
Comment		

Revision	1.2
Engineering	
Date	2012-12-19
Our Reference	





PRODUCT CONTENTS

- SERIES PRODUCTS LIST
- PHYSICAL DATA
- ABSOLUTE MAXIMUM RATINGS
- EXTERNAL DIMENSIONS
- ELECTRICAL CHARACTERISTICS
- TIMING OF POWER SUPPLY
- ELECTRO-OPTICAL CHARACTERISTICS
- INTERFACE PIN CONNECTIONS
- COMMAND TABLE
- INITIALIZATION CODE
- SCHEMATIC EXAMPLE
- RELIABILITY TESTS
- OUTGOING QUALITY CONTROL SPECIFICATION
- CAUTIONS IN USING OLED MODULE



REVISION HISTORY

Rev.	Contents	Date
1.0	First Release	2011-03-16
1.1	Update ELECTRO-OPTICAL CHARACTERISTICS	
	Update EXTERNAL DIMENSIONS	2011-05-25
	Update OUTGOING QUALITY CONTROL	
	SPECIFICATION	
1.2	Update Life Time	2012-12-19



SERIES PRODUCTS LIST

Module No.	Display	CIE		Luminance Lifetim		e (hrs@25℃)	
Iviouule Ino.	Color	X	У	typical(cd/m ²)	30% ON*	100% ON*	
MI25664FO-R	Red	0.65 ± 0.04	0.24 ± 0.04	30	150K	45K	
WII230041 O-IX	Neu	0.03 <u>+</u> 0.04	0. 34 <u>1</u> 0. 04	50	75K	22K	
MI25664FO-Y	Yellow	0.46 ± 0.05	0.51 ± 0.05	60	150K	45K	
MI23004FO-1	rellow	0.40 ± 0.05	0.51 ± 0.05	100	70K	21K	
MI25664FO-G	Green	0.31 \pm 0.04	0.62 ± 0.04	80	80K	24K	
WII25004FU-G				100	55K	16K	
MI25664FO-B		0.16 ± 0.05	0 27 + 0 05	60	80K	24K	
WII23004FO-D	Blue		0.27 ± 0.05	80	60K	18K	
MI25664FO-W	White	0.3 ± 0.05		60	80K	24K	
WII23004FO-W	willte	0.3 ± 0.05	0.30 ± 0.05	80	60K	18K	

 $\ast 30\%$ ON:30% pixels scrolling display on;100% ON:All pixels display on

 Life Time is defined when the Luminance has decayed to less than 50% of the initial Luminance

■ PHYSICAL DATA

No.	Items:	Specification:	Unit
1	Diagonal Size	2.70	Inch
2	Resolution	256(H) x 64(V)	Lines
3	Active Area	66.53 (W) x 16.61(H)	mm
4	Outline Dimension (Panel)	82.00 (W) x 25.50(H)	mm
5	Pixel Pitch	0.26 (W) x 0.26(H)	mm
6	Pixel Size	0.23 (W) x 0.23 (H)	mm
7	Driver IC	SSD1322UR1	-
8	Grayscale	4	Bit
9	Interface	Parallel / Serial	-
10	IC package type	COF with ZIF tail	-
11	Thickness	1.5 ± 0.1	mm
12	Weight	<6.5	g
13	Duty	1/64	-



■ ABSOLUTE MAXIMUM RATINGS

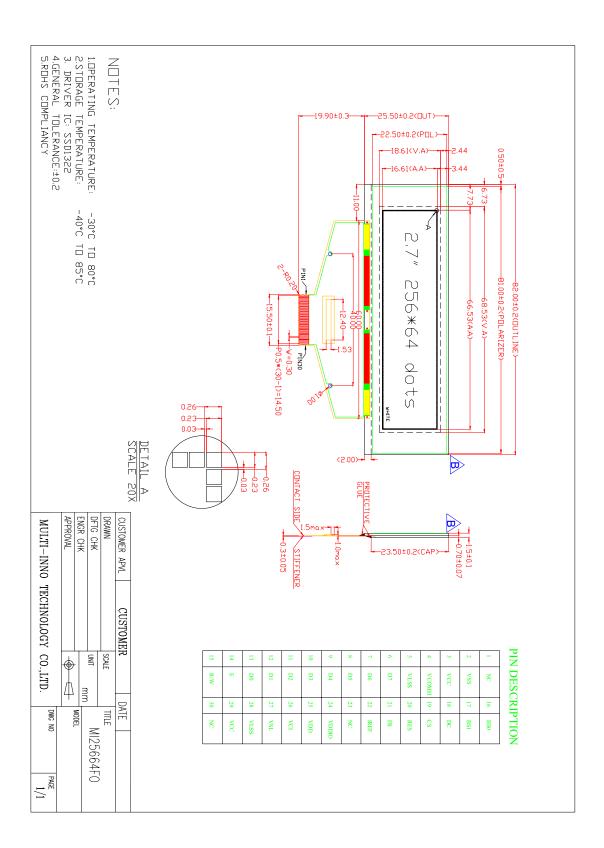
Unless oth	erwise specified		(Ta = 25°C)			
]	Items		Symbol Min Typ		Max	Unit
	I/O	V _{DDIO}	-0.5	-	V _{CI}	V
Supply	Logic	V _{CI}	-0.3	-	3.6	V
Voltage	Driving	V _{CC}	-0.5	-	21.0	V
	Core Logic	V _{DD}	-0.5	-	2.75	V
Operating	Operating Temperature		-30	-	80	°C
Storage Temperature		Tst	-40	-	85	°C
Humidity		-	-	-	90	%RH

NOTE:

Permanent device damage may occur if **ABSOLUTE MAXIMUM RATINGS** are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect reliability.



EXTERNAL DIMENSIONS





ELECTRICAL CHARACTERISTICS

• DC Characteristics

Unless othe	erwise specified,	$V_{SS} = 0V$,V _{CI} =2.4V to	(Ta = 25 °C)		
	Items		Min	Тур.	Max	Unit
	I/O	V _{DDIO}	1.65	-	V _{CI}	V
Supply	Logic	V _{CI}	2.4	3.0	3.5	V
Voltage	Operating	V _{CC}	10.0	14.0	20.0	V
	Core Logic	V _{DD}	2.4	-	2.6	
Input	High Voltage	V _{IH}	$0.8 \ x \ V_{DDIO}$	-	V _{DDIO}	V
Voltage	Low Voltage	V _{IL}	0	-	$0.2 \ x \ V_{DDIO}$	V
Output	High Voltage	V _{OH}	0.9x V _{DDIO}	-	V _{DDIO}	V
Voltage	Low Voltage	V _{OL}	0	-	$0.1 \mathrm{x} \mathrm{V}_{\mathrm{DDIO}}$	V

◆POWER CONSUMPTION

Unless otherwise specified, VSS=0V, VDD=3.0V, Frame Frequency=100Hz

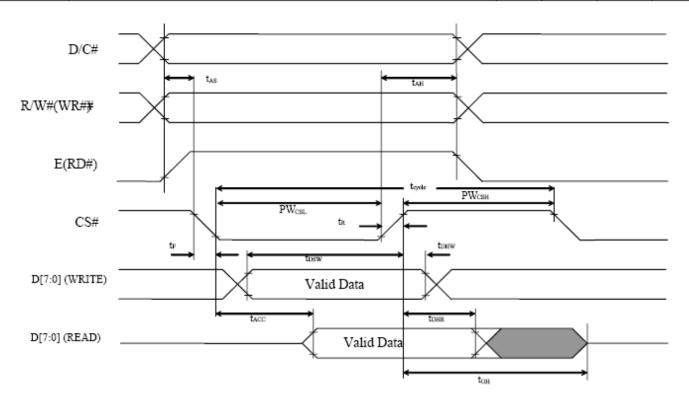
Module No.	VPP			inance (c	-	• •	f Power tion(mW)	Sleep
	(V)	Command Set(hex)	Min	Typical	Max	All pixels ON	30% pixels ON	Mode
MI25664FO-R	9.5	0x3F	25	30	_	220	80	<5uA
MI25664FO-Y	9.5	0x3F	50	60	_	220	80	<5uA
MI25664FO-G	9.5	0x3F	70	80	_	230	90	<5uA
MI25664FO-B	12.0	0x3F	50	60	Ι	380	150	<5uA
MI25664FO-W	12.0	0x3F	50	60	_	390	155	<5uA

AC Characteristics

Use 8080/6800-Series MPU Parallel Interface or Serial Interface 1. 6800 Series MPU Parallel Interface

 $(V_{DD} - V_{SS} = 2.4 \text{ to } 2.6 \text{V}, V_{DDIO} = 1.6 \text{V}, V_{CI} = 3.3 \text{V}, T_A = 25^{\circ}\text{C})$

Symbol	Parameter	Min	Тур	Max	Unit
t _{cycle}	Clock Cycle Time	300	-	-	ns
t _{AS}	Address Setup Time	10	-	-	ns
t _{AH}	Address Hold Time	0	-	-	ns
t _{DSW}	Write Data Setup Time	40	-	-	ns
t _{DHW}	Write Data Hold Time	7	-	-	ns
t _{DHR}	Read Data Hold Time	20	-	-	ns
t _{OH}	Output Disable Time	-	-	70	ns
t _{ACC}	Access Time	-	-	140	ns
DW	Chip Select Low Pulse Width (read)	120			20
PW_{CSL}	Chip Select Low Pulse Width (write)	60	-	-	ns
DW	Chip Select High Pulse Width (read)	60			20
$\mathrm{PW}_{\mathrm{CSH}}$	Chip Select High Pulse Width (write)	60	-	-	ns
t _R	Rise Time	-	-	15	ns
t _F	Fall Time	-	-	15	ns

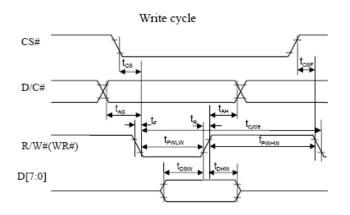


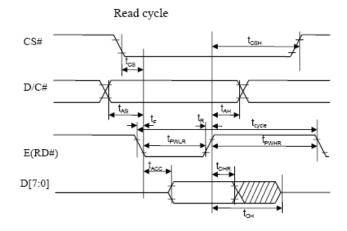


2. 8080 Series MPU Parallel Interface

 $(V_{DD} - V_{SS} = 2.4 \text{ to } 2.6 \text{V}, V_{DDIO} = 1.6 \text{V}, V_{CI} = 3.3 \text{V}, T_A = 25^{\circ}\text{C})$

Symbol	Parameter	Min	Тур	Max	Unit
t _{cycle}	Clock Cycle Time	300	-	-	ns
t _{AS}	Address Setup Time	10	-	-	ns
t _{AH}	Address Hold Time	0	-	-	ns
t _{DSW}	Write Data Setup Time	40	-	-	ns
t _{DHW}	Write Data Hold Time	7	-	-	ns
t _{DHR}	Read Data Hold Time	20	-	-	ns
t _{OH}	Output Disable Time	-	-	70	ns
t _{ACC}	Access Time	-	-	140	ns
t _{PWLR}	Read Low Time	150	-	-	ns
t _{PWLW}	Write Low Time	60	-	-	ns
t _{PWHR}	Read High Time	60	-	-	ns
t _{PWHW}	Write High Time	60	-	-	ns
t _R	Rise Time	-	-	15	ns
t _F	Fall Time	-	-	15	ns
t _{CS}	Chip select setup time	0	-	-	ns
t _{CSH}	Chip select hold time to read signal	0	-	-	ns
t _{CSF}	Chip select hold time	20	-	-	ns



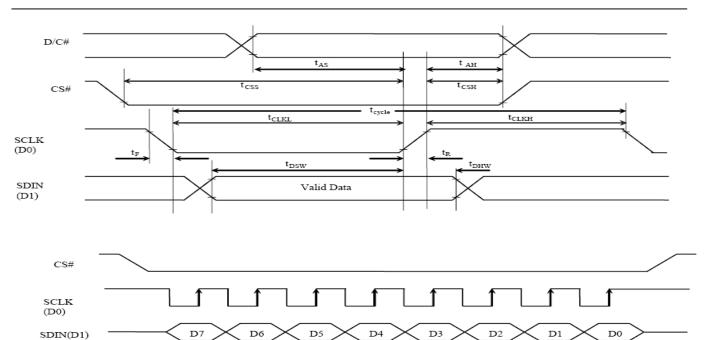


3. 4-Wire Serial Interface

 $(V_{\text{DD}}$ - V_{SS} = 2.4 to 2.6V, $V_{\text{DDIO}}\text{=}1.6V, \, V_{\text{CI}}\text{=}3.3V, \, T_{\text{A}}\text{=}25^{\circ}\text{C})$

Symbol	Parameter	Min	Тур	Max	Unit
t _{cycle}	Clock Cycle Time	100	-	-	ns
t _{AS}	Address Setup Time	15	-	-	ns
t _{AH}	Address Hold Time	15	-	-	ns
t _{css}	Chip Select Setup Time	20	-	-	ns
t _{CSH}	Chip Select Hold Time	10	-	-	ns
t _{DSW}	Write Data Setup Time	15	-	-	ns
t _{DHW}	Write Data Hold Time	15	-	-	ns
t _{CLKL}	Clock Low Time	20	-	-	ns
t _{CLKH}	Clock High Time	20	-	-	ns
t _R	Rise Time	-	-	15	ns
t _F	Fall Time	-	-	15	ns

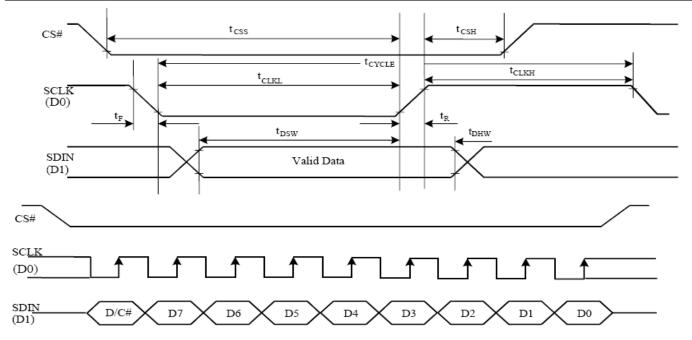




4. 3-Wire Serial Interface

 $(V_{DD}$ - V_{SS} = 2.4 to 2.6V, $V_{DDIO}{=}1.6V,\,V_{CI}$ = 3.3V, T_A = 25°C)

Symbol	Parameter	Min	Тур	Max	Unit
t _{evele}	Clock Cycle Time	100	-	-	ns
t _{css}	Chip Select Setup Time	20	-	-	ns
t _{esti}	Chip Select Hold Time	10	-	-	ns
1 _{DSW}	Write Data Setup Time	15	-	-	us
t _{DHW}	Write Data Hold Time	15	-	-	ns
t _{clkl}	Clock Low Time	20	-	-	ns
t _{elkn}	Clock High Time	20	-	-	ns
t _R	Rise Time	-	-	15	ns
t _F	Fall Time	-	-	15	ns



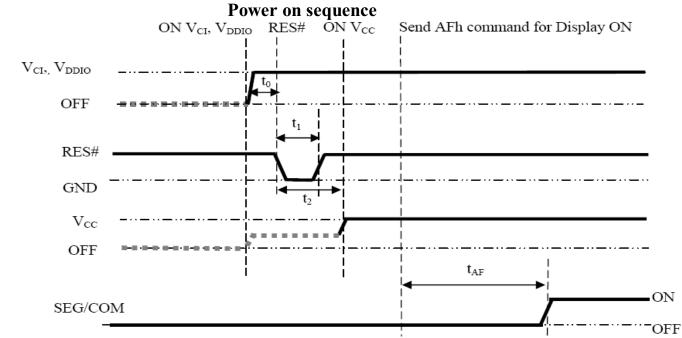


5. TIMING OF POWER SUPPLY

◆ *Power ON sequence*:

1. Power ON V_{CI}, V_{DDIO}.

2. After V_{CI} , V_{DDIO} becomes stable, set wait time at least 1ms (t₀) for internal V_{DD} become stable. Then set RES pin LOW (logic low) for at least 100us (t₁)⁽⁴⁾ and then HIGH (logic high). 3. After set RES pin LOW (logic low), wait for at least 100us (t₂). Then Power ON V_{CC} .⁽¹⁾ 4. After V_{CC} become stable, send command AFh for display ON. SEG/COM will be ON after 200ms(t_{AF}).



Power OFF sequence:

- 1. Send command AEh for display OFF.
- 2. Power OFF V_{CC}.^{(1), (2), (3)}
- 3. Wait for t_{OFF}. Power OFF V_{CI}, V_{DDIO}.(where Minimum t_{OFF}=0ms (5), Typical t_{OFF}=100ms)

Note:

 $^{(1)}$ Since an ESD protection circuit is connected between V_{CI} , V_{DDIO} and V_{CC} , V_{CC} becomes lower than V_{CI} whenever V_{CI} , V_{DDIO} is ON and V_{CC} is OFF as shown in the dotted line of V_{CC} in Figure above.

 $^{(2)}V_{CC}$ should be kept float (disable) when it is OFF.

 $^{(3)}$ Power pins (V_{CI}, V_{CC}) can never be pulled to ground under any circumstance.

⁽⁴⁾ The register values are reset after t_1 .

⁽⁵⁾ VCI, V_{DDIO} should not be Power OFF before VCC Power OFF.



ELECTRO-OPTICAL C	HARAC	TERISTI	CS (Ta	1=25℃)	

Items		Symbol	Min.	Тур.	Max.	Unit	Remark			
Operating Lumi	nance	L	90	100*	-	cd /m ²	White			
Power Consum	ntion	Р		280	290	XX 7	30% pixels on			
rower Collsuin	ption	Г	-	280		mW	L=100 cd/m ²			
Frame Freque	ncy	Fr	-	100	-	Hz				
Color Coordinate	White	CIE x	0.255	0.295	0.335	CIE1931	Darkroom			
	vv mte	CIE y	0.295	0.335	0.375	CIE1951				
Response Time	Rise	Tr	-	-	0.02	ms	-			
Kesponse Time	Decay	Td	-	-	0.02	ms	-			
Contrast Rat	io	Cr	10000:1	-	-		Darkroom			
Viewing Angle Ur	niformity	θ	160	-	-	Degree	-			
Operating Life	Гime	_	20,000	-	-	Hours	L=100cd/m ²			

Note:

1. 100 cd/m² is based on V_{CI} =3.0V, V_{CC} =14.0V, contrast command setting 0xCF.

2. Contrast ratio is defined as follows:

Contrast ratio = _____Photo – detector output with OLED being "white"

Photo – detector output with OLED being "black"

3. Life Time is defined when the Luminance has decayed to less than 50% of the initial Luminance specification. (30% pixels scrolling display on)

(The initial value should be closed to the typical value after adjusting.)



■ INTERFACE PIN CONNECTIONS

No	Symbol	Description							
1	NC	No connection							
2	VSS	Ground. Common Voltage Reference Pin							
3	VCC	Power supply for panel driving voltage. Segment voltage							
4	VCOMH	COM signal deselected voltage level. High Level Voltage Output Of COM Signal							
5	VLSS	Analog system ground pin. Voltage Supply							
6-13	D7-D0	These pins are bi-directional data bus connecting to the MCU data bus. Unused pins are recommended to tie LOW. (Except for D2 pin in SPI mode, D2 is pulled low in SPI mode).							
14	E (RD)	MCU Interface Input pin, in 6800 parallel mode, it is used as enable signal, read/write operation is initiated when this pin is set high with chip selected. In 8080 parallel mode, this pin receives read signal, read operation is initiated when this is pulled low with chip selected. When SPI interface is selected, this pin must be connected to ground.							
15	R/W(WR)	MCU Interface Input pin, in 6800 parallel mode, it is used as read/write selection input, read mode will be carried out when This pin is pulled high while write mode with this pin pulled low. In 8080 parallel mode, this pin will be write input, write operation is initiated when this is pulled low with chip selected. When SPI interface is selected, this pin must be connected to ground.							
16- 17	BS0-1	MCU bus interface selection pins. Select appropriate logicsetting as described in the following table.BS[1:0]Bus Interface Selection004 line SPI013 line SPI108-bit 8080 parallel118-bit 6800 parallel							
18	D/C	This pin is Data/Command control pin connected to the MCU. When the pin is pulled HIGH, the content at D 7:0 will be interpreted as data. When the pin is pulled LOW, the content at D 7:0 will be interpreted as command.							
19	CS	This pin is the chip select input connected to the MCU. The chip is enabled for MCU communication only when CS is pulled LOW.							
20	RES	This pin is reset signal input. When the pin is pulled LOW, initialization of the chip is executed. Keep this pin pull HIGH during normal operation.							



21	FR	This pin is No Connection pins. Nothing should be connected to this pin. This pin should be left open individually.
22	IREF	This pin is the segment output current reference pin. A resistor should be connected between this pin and VSS to maintain the current around 10uA.
23	NC	No connection.
24	VDDIO	Power supply for interface logic level. It should be matched with the MCU interface voltage level.
25	VDD	Power supply pin for core logic operation. A capacitor is required to connect between this pin and VSS.
26	VCI	Low voltage power supply. VCI must always be equal to or higher than VDD and VDDIO.
27	VSL	This is segment voltage reference pin. When external VSL is used, connect with resistor and diode to ground
28	VLSS	Analog system ground pin.
29	VCC	Power supply for panel driving voltage. Segment Voltage
30	NC	No Connection.

COMMAND TABLE

D / C #	Hex	D 7	D6	D5	D4	D3	D2	D2	D 0	Command	Description
0	00	0	0	0	0	0	0	0	0	Enable Gray	This command is sent to enable the Gray Scale table setting
Ŭ	00	Ŭ	Ŭ	Ŭ	Ŭ	Ŭ		0			(command B8h)
0	15	0	0	0	1	0	1	0	1		Set Column start and end address
1	A[6:0]	*	A ₆	A_5	A_4	A_3	A_2	A_1	A ₀	Set Column	A[6:0]: Start Address. [reset=0]
1	B[6:0]	*	B ₆	B ₅	B_4	B ₃	B_2	B_1	B ₀		B[6:0]: End Address. [reset=119] Range from 0 to 119
0	5C	0	1	0	1	1	1	0	0	Write RAM Command	Enable MCU to write Data into RAM
0	5D	0	1	0	1	1	1	0	1		
Ŭ	50	0	1	0	1	1	1	0		Read RAM Command	Enable MCU to read Data from RAM
0	75	0	1	1	1	0	1	0	1		Set Row start and end address
1	A[6:0]	*	A ₆	A ₅	A_4	A_3	A_2	A_1	A ₀	Set Row	A[6:0]: Start Address. [reset=0]
1	B[6:0]	*	B ₆	B ₅	B ₄	B3	B_2	B1	B ₀	Address	B[6:0]: End Address. [reset=127]
			Ű		-		2		Ů		Range from 0 to 127
0	A0	1	0	1	0	0	0	0	0		A[0]=0b, Horizontal address increment [reset]
1	A[7:0]	0	0	A_5	A_4	0	A_2	A_1	A ₀		A[0]=1b, Vertical address increment
1	B[4]	*	*	0	B ₄	0	0	0	1		A[1]=0b, Disable Column Address Re-map [reset]
											A[1]=00, Disable Column Address Re-map [reset] A[1]=1b, Enable Column Address Re-map
											A[2]=0b, Disable Nibble Re-map [reset]
											A[2]=00, Disable Nibble Re-map A[2]=1b, Enable Nibble Re-map
											A[4]_0h_Som form COM0 to COMDU 11[mont]
											A[4]=0b, Scan from COM0 to COM[N -1] [reset] A[4]=1b, Scan from COM[N-1] to COM0, where N is the
											Multipley ratio
										Set Re-map and Dual COM Line	-
										mode	A[5]=00, Disable COM Split Odd Even [reset]
										mode	A[5]=1b, Enable COM Split Odd Even
											B[4], Enable / disable Dual COM Line mode
											0b, Disable Dual COM mode [reset]
											1b, Enable Dual COM mode (MUX ≤ 63)
											Note
											⁽¹⁾ COM Split Odd Even mode must be disabled (A[5]=0b)
											when enabling the Dual COM mode (B[4]=1b)
											Details refer to Section 10.1.6
0	A1	1	0	1	0	0	0	0	1		
1	A[6:0]	*	A_6	A ₅	A_4	A ₃	A_2	A_1	A ₀	Set Display	Set display RAM display start line register from 0-127
	[]						2	1		Start Line	Display start line register is reset to 00h after RESET



D / C #	Hex	D 7	D6	D5	D4	D3	D2	D2	D 0	Command	Description	
0	A2	1	0	1	0	0	0	1	0	G (D) 1		
1	A[6:0]	*	A ₆	A5	A ₄	A3	A ₂	A_l	A ₀	Set Display Offset	Set vertical scroll by COM from 0-127 The value is reset to 00H after RESET	
0	A4~A7	1	0	1	0	0	X_2	X_1	X ₀		A4h = Entire Display OFF, all pixels turns OFF in GS level 0	
											A5h = Entire Display ON, all pixels turns ON in GS level 15	
										Set Display Mode	A6h = Normal Display [reset]	
											A7h = Inverse Display (GS0 → GS15, GS1 → GS14, GS2 → GS13,)	
0	A8	1	0	1	0	1	0	0	0		This command turns ON partial mode. The partial mode	
1	A[6:0]	0	A_6	A_5	A_4	A_3	A_2	A_1	A ₀	Enable Partial	display area is defined by the following two parameters,	
1	B[6:0]	0	B_6	B_5	B ₄	B ₃	B ₂	B_1	B ₀	Display	A[6:0]: Address of start row in the display area	
										Disping	B[6:0]: Address of end row in the display area,	
											where $B[6:0]$ must be $\geq A[6:0]$	
0	A9	1	0	1	0	1	0	0	1	Exit Partial	This command is sent to exit the Partial Display mode	
		1	0		0	1		1	1	Display		
0	AB A[0]	1 0	0	1 0	0	1	0	1 0	1 A0	Function	A[0]=0b, Select external V _{DD}	
	A[V]	0	0	Ŭ	Ŭ	Ŭ	0	U	A0	Selection	A[0]=1b, Enable internal V _{DD} regulator [reset]	
0	AE~AF	1	0	1	0	1	1	1	\mathbf{X}_{0}	Set Sleen mode	AEh = Sleep mode ON (Display OFF)	
											AFh = Sleep mode OFF (Display ON)	
0	B1	1	0	1	1	0	0	0	1		A[3:0] Phase 1 period (reset phase length) of 5~31 DCLK(s)	
1	A[7:0]	A7	A ₆	A_5	A_4	A3	A_2	A_1	A ₀		clocks as follow:	
											A[3:0] Phase 1 period	
											0000 invalid	
											0001 invalid 0010 5 DCLKs	
											0011 7 DCLKs	
											0100 9 DCLKs [reset]	
											: : 1111 31 DCLKs	
											1111 STDCLKS	
										Set Phase		
										Length	A[7:4] Phase 2 period (first pre-charge phase length) of 3~15 DCLK(s) clocks as follow:	
											A[7:4] Phase 2 period	
											0000 invalid	
											0001 invalid	
											0010 invalid	
											0011 3 DCLKs	
											0111 7 DCLKs [reset]	
											1111 15 DCLKs	



D/C#

Hex	D 7	D6	D5	D4	D3	D2	D2	D 0	Command	Description
B3	1	0	1	1	0	0	1	1		A[3:0] [reset=0], divide by DIVSET where
B3 A[7:0]	1 A7	0 A ₆	1 A5	1 A4	0 A3	0 A ₂	1 A1	1 A ₀	Set Front Clock Divider / Oscillator Frequency	A[3:0] DIVSET 0000 divide by 1 0001 divide by 2 0010 divide by 4 0011 divide by 8 0100 divide by 16 0101 divide by 32
B4 A[1:0] B[7:3]	1 1 B ₇	0 0 B ₆	1 1 B ₅	1 0 B ₄	0 0 B ₃	1 0 1	0 A ₁ 0	0 A ₀ 1	Display Enhancement A	A[1:0] = 00b: Enable external VSL A[1:0] = 10b: Internal VSL [reset] B[7:3] = 11111b: Enhanced low GS display quality B[7:3] = 10110b: Normal [reset]
B5 A[3:0]	1 *	0 *	1 *	1 *	0 A3	1 A2	0 A1	1 A ₀	A[1:0] GPIO0: 00 pin HiZ, Input disabled 01 pin HiZ, Input enabled 10 pin output LOW [reset] 11 pin output HIGH Set GPIO A[3:2] GPIO1: 00 pin HiZ, Input disabled 01 pin HiZ, Input disabled 10 pin output LOW [reset] 11 pin output HIGH	
B6 A[3:0]	1 *	0 *	1 *	1 *	0 A ₃	1 A ₂	1 A1	0 A ₀	Set Second Precharge Period	A[3:0] Second Pre-charge period 0000b 0 dclk 0001b 1 dclk 1000b 8 dclks [reset] 1111b 15 dclks



D/C#	Hex	D 7	D6	D5	D4	D3	D2	D2	D 0	Command	Description
0	B8	1	0	1	1	1	0	0	0		The next 15 data bytes define Gray Scale (GS) Table by
1	A1[7:0]	$A1_7$	A16	A1,	A14	A13	A12	$A1_1$	A1 ₀		setting the gray scale pulse width in unit of DCLK's
1	A2[7:0]		A26	A25	A24	A23	A22	A21	A20		(ranges from 0d ~ 180d)
1										Set Grav Scale	A 1[7:0]: Commo Soffice for CS1
1										Table	A1[7:0]: Gamma Setting for GS1, A2[7:0]: Gamma Setting for GS2,
1											A2[7.0]. Gamma Seamg for G52,
1	A14[7:0]	A147	A146	A145	A144	A143	A142	A141	A140		A14[7:0]: Gamma Setting for GS14,
1	A15[7:0]								A150		A15[7:0]: Gamma Setting for GS15
	1110[7.0]	,		,		,					
											Note ^{(1]} 0 ≤ Setting of GS1 < Setting of GS2 < Setting of GS3
											< Setting of GS14 < Setting of GS15
											secting of doi: 1 secting of doi:
											Refer to Section 8.8 for details
											^{(2]} The setting must be followed by the Enable Gray Scale
											Table command (00h)
0	B9	1	0	1	1	1	0	0	1		The default Linear Gray Scale table is set in unit of DCLK's
Ŭ	2,	•	Ŭ	-	-	-	Ŭ	Ŭ	-		as follow
											GS0 level pulse width = 0 ;
											GS1 level pulse width = 0; GS2 level pulse width = 8;
										Select Default	GS3 level pulse width = 16;
										Linear Gray	:
										Scale table	:
											GS14 level pulse width = 104; GS15 level curles width = 112
											GS15 level pulse width = 112
											Refer to Section 8.8 for details
0	BB	1	0	1	1	1	0	1	1		Set pre-charge voltage level.[reset = 17h]
1	A[4:0]	*	*	*	A4	A ₃	A_2	A_1	A_0		
										a / D 1	A[4:0] Hex code pre-charge voltage
										Set Pre-charge voltage	00000 00h 0.20 x V _{CC}
										vonage	11111 1Fh 0.60 x V _{CC}
0	BE	1	0	1	1	1	1	1	0		Set COM deselect voltage level [reset = 04h]
1	A[2:0]	*	*	*	*	0	A ₂	A ₁	A ₀		
1	A[2.0]				-		A ₂	A	A0		A[2:0] Hex code V _{COMH}
											000 00h 0.72 x V _{CC}
										Set V _{COMH}	: : :
											100 04h 0.80 x V _{CC} [reset]
											111 07h 0.86 x V _{CC}
	C1	1	1		_		0		1		A[7:0]: Contrast current value, range:00h~FFh,
0	C1	1	1	0	0	0	0	0	1	Set Contrast	i.e. 256 steps for I _{SEG} current [reset = 7Fh]
1	A[7:0]	A7	A ₆	A ₅	A4	A ₃	A_2	A_1	A ₀	Current	reaction of the reaction of the content [react = /1 n]



Ver	1.2
-----	-----

D/C#	Hex	D 7	D6	D5	D4	D3	D2	D2	D 0	Command	Description
0	C7	1	1	0	0	0	1	1	1		A[3:0] =
1	A[3:0]	*	*	*	*	A3	A_2	A_1	A ₀	Master Contrast	0000b, reduce output currents for all colors to 1/16 0001b, reduce output currents for all colors to 2/16
										Current Control	
0	CA	1	1	0	0	1	0	1	0		A[6:0]: Set MUX ratio from 16MUX ~ 128MUX
1	A[6:0]	*	A ₆	A5	A4	A3	A ₂	A_1	A ₀	Set MUX Ratio	A[6:0] = 15d represents 16MUX
											A[6:0] = 127d represents 128MUX [reset]
0	D1	1	1	0	1	0	0	0	1		
1	A[5:4]	1	0	A_5	A_4	0	0	1	0		A[5:4] = 00b: Reserved
1	20	0	0	1	0	0	0	0	0	Enhancement B	A[5:4] = 10b: Normal [reset]
0	FD	1	1	1	1	1	1	0	1		A[2]: MCU protection status [reset = 12h]
1	A[2]	0	0	0	1	0	A ₂	1	0	Set Command Lock	A[2] = 0b, Unlock OLED driver IC MCU interface from entering command [reset] A[2] = 1b, Lock OLED driver IC MCU interface from entering command
											Note (1) The locked OLED driver IC MCU interface prohibits all commands and memory access except the FDh command



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■ INITIALIZATION CODE

void Inital_SSD1322()

```
\label{eq:WMLCDCOM(0xFD);//Command lock setting} $$ WMLCDDATA(0x12); $$
```

WMLCDCOM(OxAE);//Display OFF

 $\label{eq:WMLCDCOM(0x15);//column address setting} $$ WMLCDDATA(0x1C); $$ WMLCDDATA(0x5B); $$ WMLCDDATA(0x5B); $$ The setting term of te$

 $\label{eq:WMLCDCOM(0x75);//row address setting} $$ WMLCDDATA(0x00); $$ WMLCDDATA(0x3F); $$ WMLCDDATA(0x3F); $$ The setting term of term$

 $\label{eq:WMLCDCOM(0xA0);//re_map&dual com mode} $$ WMLCDDATA(0x14); $$ WMLCDDATA(0x11);//enable dual com mode $$ WMLCDDATA(0x11); //enable dual com mode $$ WMLCDDATA(0x11); //enable dual com mode $$ WMLCDDATA(0x11); //enable dual com mode $$ WMLCDDATA(0x11); WMLCDDATA(0x11); % WMLCDDATA(0x11); % WMLCDDATA[V] $$ WMLCDDATA[$

```
\label{eq:WMLCDCOM(0xA1);//display start line} $$ WMLCDDATA(0x00); $$
```

```
WMLCDCOM(0xA2);//display offset
WMLCDDATA(0x00);
```

```
WMLCDCOM(0xA6);//normal display
```

```
//WMLCDCOM(0xA8);//partial display setting
//WMLCDDATA(0x00);//start row
//WMLCDDATA(0x3F);//end row
```

```
//WMLCDCOM(0xA9);//exit partial display mode
```

```
WMLCDCOM(0xAB);//function selection
WMLCDDATA(0x01);//enable internal vdd
```

```
WMLCDCOM(0xB1);//phase length setting
WMLCDDATA(0x74);//phase1=9dclk.phase2=7dclk
```



```
WMLCDCOM(0xB3)://front clock divider&oscillator freq
WMLCDDATA (0x51):
WMLCDCOM(0xB4);//display enhancement A
WMLCDDATA (0xA2) : //INTERNAL VSL
WMLCDDATA(0xB5);//normal or 11111101 to enhance low GS
//WMLCDCOM(0xB5)://GPI0 SETTING
//WMLCDDATA(0x0a);
WMLCDCOM(0xB6);//second precharge period setting
WMLCDDATA (0x08);
WMLCDCOM(0xBB);//set precharge voltage
WMLCDDATA (0x17);
WMLCDCOM(0xBE);//set VCOMH voltage
WMLCDDATA (0x04) ; //0. 80*VCC
WMLCDCOM(0xC1);//contrast set
WMLCDDATA (CONTRAST);
WMLCDCOM(0xC7);//master current set
WMLCDDATA (0x0F);
WMLCDCOM(0xCA);//mux set
WMLCDDATA (0x3F);
WMLCDCOM(0xD1);//display enhancement B
WMLCDDATA (0xA2) ;
WMLCDDATA (0x20);
WMLCDCOM(0x00);//enable gray scale setting
WMLCDCOM(0xB8);//gray scale setting
WMLCDDATA (0x00) ; //GS1=0
WMLCDDATA (0x0C);//GS2=8
WMLCDDATA (0x18); //GS3=8
WMLCDDATA (0x24);//GS4=8
WMLCDDATA (0x30); //GS5=9
WMLCDDATA (0x3C) : //GS6=9
```



WMLCDDATA (0x48);//GS7=9 WMLCDDATA (0x54);//GS8=10 WMLCDDATA (0x60);//GS9=10 WMLCDDATA (0x6C);//GS10=10 WMLCDDATA (0x78);//GS11=10 WMLCDDATA (0x84);//GS12=10 WMLCDDATA (0x90);//GS13=11 WMLCDDATA (0x9C);//GS14=11 WMLCDDATA (0xA8);//GS15=12

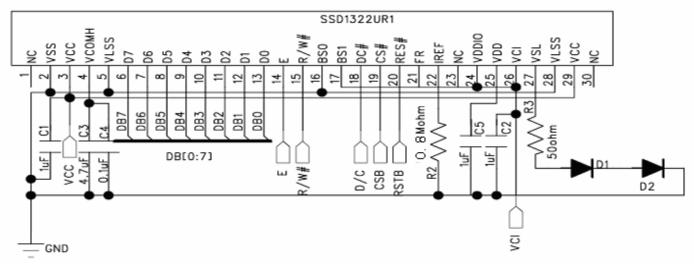
WMLCDCOM(OxAF);//Display ON

Note:

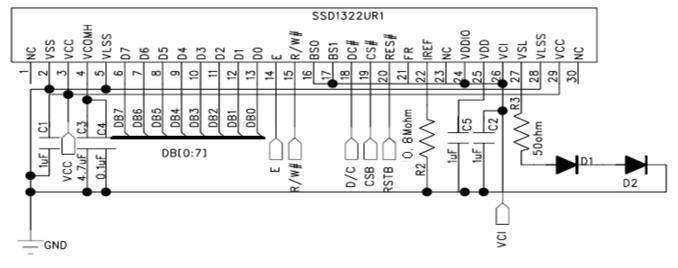
}

Set appropriate parameters of initialization base on actual application. ■ SCHEMATIC EXAMPLE

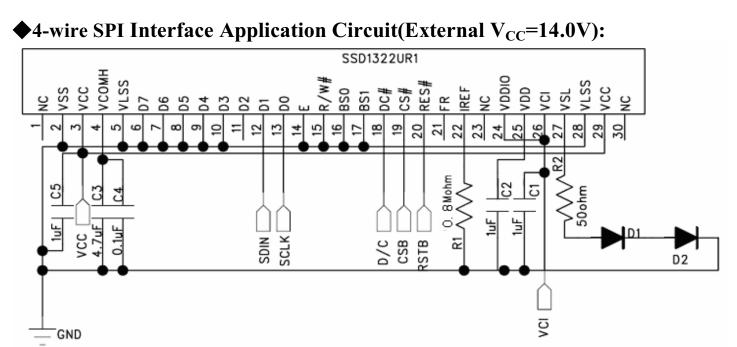
♦8080 Series Interface Application Circuit(External V_{CC}=14.0V):



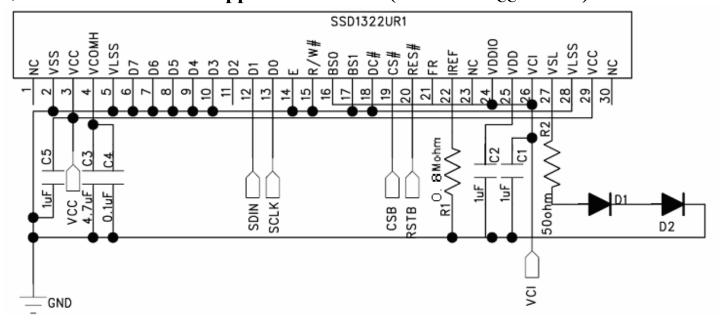
6800 Series Interface Application Circuit(External V_{CC}=14.0V):







◆3-wire SPI Interface Application Circuit(External V_{CC}=14.0V):



NOTE:

Voltage at IREF = VCC – 6V. For VCC = 14V, IREF = 10uA : R1 = (Voltage at IREF - VSS) / IREF= (14 - 6) / 10u= $0.8M\Omega$ R2 = 50Ω , $1/8W^{(1)}$ D1 - D2 = Vth = 0.7V, $1N4148^{(1)}$

C1 ~ C2, C3, C5: 4.7uF, C4: 0.1uF

Note

(1) The value is recommended value. Select appropriate value against module application.



RELIABILITY TESTS

	Item	Condition	Criterion			
High Te	emperature Storage (HTS)	$80\pm2^{\circ}$ C, 200 hours	 After testing, the function test is ok. After testing, no addition to the defect. 			
High Ter	mperature Operating (HTO)	$70\pm2^{\circ}$ C, 96 hours	 3. After testing, the change of luminance should be within +/- 50% of initial value. 			
Low Te	emperature Storage (LTS)	-30±2°C, 200 hours	4. After testing, the change for the mono and area color must be			
Low Ter	nperature Operating (LTO)	-20±2°C, 96 hours	 within (+/-0.02, +/- 0.02) and for the full color it must be within (+/-0.04, +/-0.04) of initial value based on 1931 CIE coordinates. 5. After testing, the change of total current consumption should be within +/- 50% of initial value. 			
High Tempo	erature / High Humidity Storage (HTHHS)	50±3°C, 90%±3%RH, 120 hours				
Thermal S	hock (Non-operation) (TS)	-20±2°C ~ 25°C ~ 70±2°C (30min) (5min) (30min) 10cycles				
Vibration (Packing)	10~55~10Hz,amplitu de 1.5mm, 1 hour for each direction x, y, z	1. One box for each test.				
Drop (Packing)	Height : 1 m, each time for 6 sides, 3 edges, 1 angle	2. No addition to the cosmetic and the electrical defects.				
ESD (finished product housing)	±4kV (R: 330Ω C: 150pF , 10times, air discharge)	 After testing, cosmetic and electrical defects should not happen. In case of malfunction or defect caused by ESD damage, it would be judged as a good part if it would be recovered to normal state after resetting. 				

Note: 1) For each reliability test, the sample quantity is 3, and only for one test item.

2) The HTHHS test is requested the Pure Water(Resistance>10M Ω).

3) The test should be done after 2 hours of recovery time in normal environment.



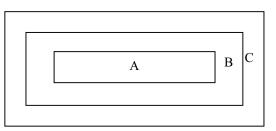
OUTGOING QUALITY CONTROL SPECIFICATION

◆Standard

According to GB/T2828.1-2003/ISO 2859-1: 1999 and ANSI/ASQC Z1.4-1993, General Inspection Level II.

Definition

- 1 Major defect : The defect that greatly affect the usability of product.
- 2 Minor defect : The other defects, such as cosmetic defects, etc.
- 3 Definition of inspection zone:



Zone A: Active Area

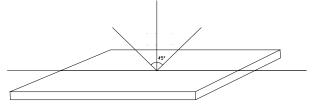
Zone B: Viewing Area except Zone A

Zone C: Outside Viewing Area

Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble of quality and assembly to customer s product.

Inspection Methods

1 The general inspection : under 20W x 2 or 40W fluorescent light, about 30cm viewing distance, within 45° viewing angle, under 25±5°C.



2 The luminance and color coordinate inspection : By PR705 or BM-7 or the equal equipments, in the dark room, under $25\pm5^{\circ}$ C.

♦Inspection Criteria

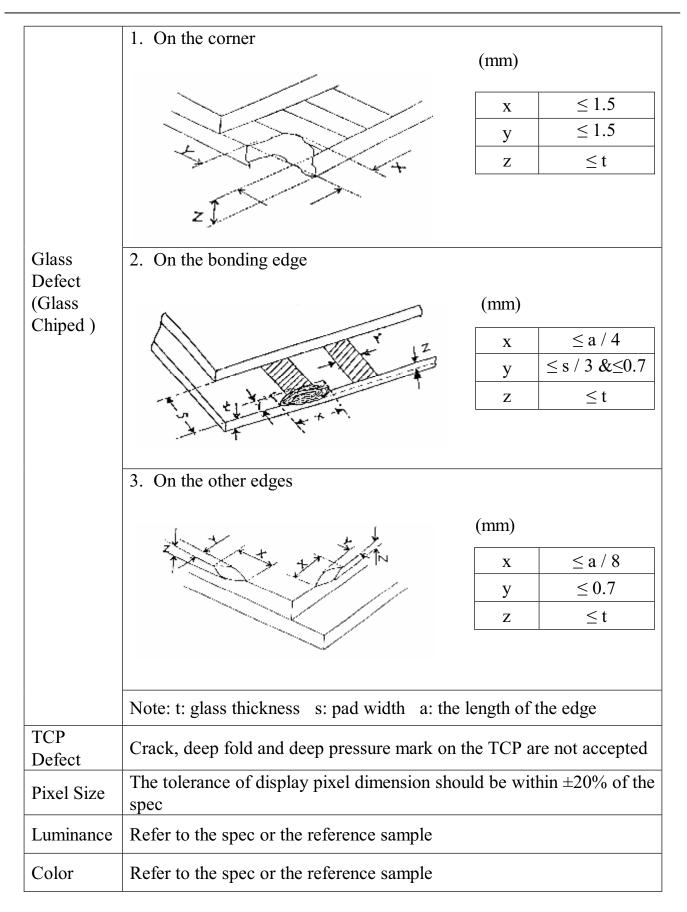
1 Major defect : AQL= 0.65

Item	Criterion						
	1. No display or abnormal display is not accepted						
Function Defect	2. Open or short is not accepted.						
	3. Power consumption exceeding the spec is not accepted.						
Outline Dimension	Outline dimension exceeding the spec is not accepted.						
Glass Crack	Glass crack tends to enlarge is not accepted.						



	Criterion				
Spot Defect (dimming and lighting spot)	Size (mm)		Accepted Qty		
			Area A + Area B	Area C	
		$\Phi \! \leq \! 0.07$	Ignored		
	Y X	$0.07 < \Phi \le 0.10$	3	Ignored	
		0.10<Φ≦0.15	1		
		0.15<Φ	0		
	Note : $\Phi = (x + y) /$	2			
Line Defect (dimming and lighting line)	L (Length):mm	W (Width):mm	Area A + Area B	Area C	
	/	W≦0.02	Ignored	Ignored	
	L≦3.0	$0.02 \le W \le 0.03$	2	Ignored	
	L≦2.0	$0.03 \le W \le 0.05$	1		
	/	0.05 <w< td=""><td>As spot defect</td></w<>	As spot defect		
distance bet Polarizer Stain	ween two lines defects must exceed 1 mmStain which can be wiped off lightly with a soft cloth or similar cleaning is accepted, otherwise, according to the Spot Defect and the				
Polarizer Scratch	Line Defect.1. If scratch can be seen during operation, according to the criterions of the Spot Defect and the Line Defect.				
	2. If scratch can be seen only under non-operation or some special angle, the criterion is as below :				
	L (Length): mm	W (Width):mm	Area A + Area B		
				Area C	
	/	W≦0.02	Ignore	Area C	
	/ 3.0 <l≦5.0< td=""><td>$W \le 0.02$ 0.02 $< W \le 0.04$</td><td>Ignore 2</td><td>Area C</td></l≦5.0<>	$W \le 0.02$ 0.02 $< W \le 0.04$	Ignore 2	Area C	
	/ 3.0 <l≦5.0 L≦3.0</l≦5.0 		-	Area C Ignore	
		$0.02 \le W \le 0.04$	2		
	L≦3.0 ∕	$0.02 < W \le 0.04$ 0.04 < W \le 0.06	2		
Dalari	L≦3.0 /	$0.02 < W \le 0.04$ $0.04 < W \le 0.06$ 0.06 < W	2 1 0	Ignore	
Polarizer Air Bubble	L≦3.0 ∕	$0.02 < W \le 0.04$ 0.04 < W \le 0.06 0.06 < W ze	2 1 0 Area A + Area B	Ignore Area C	
Polarizer Air Bubble	L≦3.0 /	$0.02 < W \le 0.04$ 0.04 < W \le 0.06 0.06 < W ze $\Phi \le 0.20$	2 1 0 Area A + Area B Ignored	Ignore	







CAUTIONS IN USING OLED MODULE

Precautions For Handling OLED Module:

1. OLED module consists of glass and polarizer. Pay attention to the following items when handling:

- i. Avoid drop from high, avoid excessive impact and pressure.
- ii. Do not touch, push or rub the exposed polarizers with anything harder than an HB pencil lead.
- iii. If the surface becomes dirty, breathe on the surface and gently wipe it off with a soft dry cloth. If it is terrible dirty, moisten the soft cloth with Isopropyl alcohol or Ethyl alcohol. Other solvents may damage the polarizer. Especially water, Ketone and Aromatic solvents.
- iv. Wipe off saliva or water drops immediately, contact the polarizer with water over a long period of time may cause deformation.
- v. Please keep the temperature within specified range for use and storage. Polarization degradation, bubble generation or polarizer peeling-off may occur with high temperature and high humidity.
- vi. Condensation on the surface and the terminals due to cold or anything will damage, stain or dirty the polarizer, so make it clean as the way of iii.
- 2. Do not attempt to disassemble or process the OLED Module.
- 3. Make sure the TCP or the FPC of the Module is free of twisting, warping and distortion, do not pull or bend them forcefully, especially the soldering pins. On the other side, the SLIT part of the TCP is made to bend in the necessary case.
- 4. When assembling the module into other equipment, give the glass enough space to avoid excessive pressure on the glass, especially the glass cover which is much more fragile.
- 5. Be sure to keep the air pressure under 120 kPa, otherwise the glass cover is to be cracked.
- 6. Be careful to prevent damage by static electricity:
 - i. Be sure to ground the body when handling the OLED Modules.
 - ii. All machines and tools required for assembling, such as soldering irons, must be properly grounded.
 - iii. Do not assemble and do no other work under dry conditions to reduce the amount of static electricity generated. A relative humidity of 50%-60% is recommended.
 - iv. Peel off the protective film slowly to avoid the amount of static electricity generated.
 - v. Avoid to touch the circuit, the soldering pins and the IC on the Module by the body.
 - vi. Be sure to use anti-static package.
- 7. Contamination on terminals can cause an electrochemical reaction and corrade the terminal circuit, so make it clean anytime.
- 8. All terminals should be open, do not attach any conductor or semiconductor on the terminals.
- 9. When the logic circuit power is off, do not apply the input signals.
- 10. Power on sequence: $V_{DD} \rightarrow V_{CC}$, and power off sequence: $V_{CC} \rightarrow V_{DD}$.
- 11. Be sure to keep temperature, humidity and voltage within the ranges of the spec, otherwise shorten Module' s life time, even make it damaged.
- 12. Be sure to drive the OLED Module following the Specification and datasheet of IC controller, otherwise something wrong may be seen.



13. When displaying images, keep them rolling, and avoid one fixed image displaying more than 30 seconds, otherwise the residue image is to be seen. This is the speciality of OLED.

Precautions For Soldering OLED Module:

- 1. Soldering temperature : $260^{\circ}C \pm 10^{\circ}C$.
- 2. Soldering time : 3-4 sec.
- 3. Repeating time : no more than 3 times.
- 4. If soldering flux is used, be sure to remove any remaining flux after finishing soldering operation. (This does not apply in the case of a non-halogen type of flux.) It is recommended to protect the surface with a cover during soldering to prevent any damage due to flux spatters.

Precautions For Storing OLED Module:

- 1. Be sure to store the OLED Module in the vacuum bag with dessicant.
- 2. If the Module can not be used up in 1 month after the bag being opened, make sure to seal the Module in the vacuum bag with dessicant again.
- 3. Store the Module in a dark place, do not expose to sunlight or fluorescent light.
- 4. The polarizer surface should not touch any other objects. It is recommended to store the Module in the shipping container.
- 5. It is recommended to keep the temperature between 0°C and 30°C , the relative humidity not over 60%.

◆ Limited Warranty

Unless relevant quality agreements signed with customer and law enforcement, for a period of 12 months from date of production, all products (except automotive products)Multi-Inno will replace or repair any of its OLED modules which are found to be functional defect when inspected in accordance withMulti-Inno OLED acceptance standards (copies available upon request). Cosmetic/visual defects must be returned to Multi-Inno within 90 days of shipment. Confirmation of such date should be based on freight documents. The warranty liability of Multi-Inno is limited to repair and/or replacement on the terms above.Multi-Inno will not be responsible for any subsequent or consequential events.

Return OLED Module Under Warranty:

- 1. No warranty in the case that the precautions are disregarded.
- 2. Module repairs will be invoiced to the customer upon mutual agreement. Modules must be returned with sufficient description of the failures or defects.

♦ PRIOR CONSULT MATTER

- 1. For Multi-Inno standard products, we keep the right to change material ,process ... for improving the product property without any notice on our customer.
- 2. If you have special requirement about reliability condition, please let us know before you start the test on our samples.